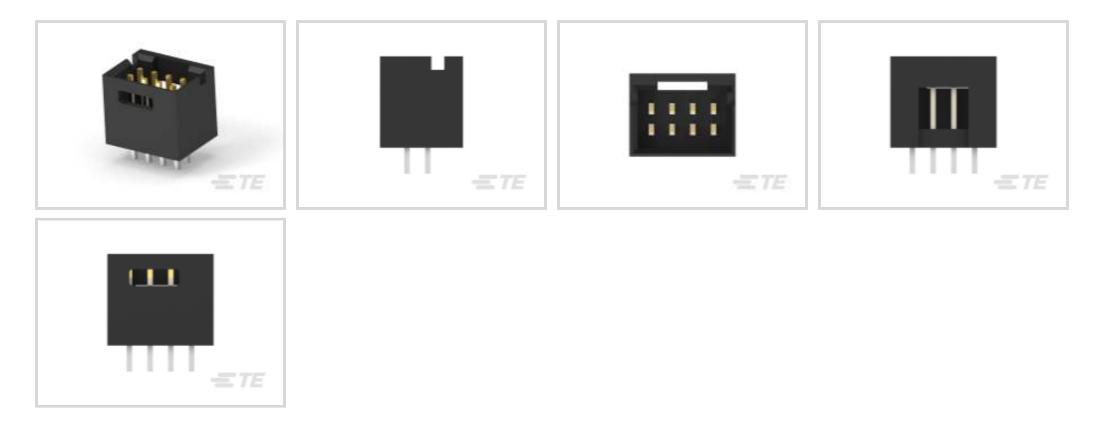
# 103168-2 - ACTIVE

#### AMPMODU | AMPMODU Headers

TE Internal #: 103168-2 PCB Mount Header, Vertical, Board-to-Board, 8 Position, 2.54 mm [. 1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers

#### View on TE.com >

Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 8

Number of Rows: 2

### Features

**Connectivity** 

### **Product Type Features**

PCB Connector Assembly Type	PCB Mount Header	
Connector System	Board-to-Board	
Header Type	Fully Shrouded	
Connector & Contact Terminates To	Printed Circuit Board	
Configuration Features		
Connector Contact Load Condition	Fully Loaded	
PCB Mount Orientation	Vertical	
Number of Positions	8	
Number of Rows	2	
Board-to-Board Configuration	Parallel	
Electrical Characteristics		
Insulation Resistance	5000 MΩ	
Dielectric Withstanding Voltage (Max)	750 Vrms	
Body Features		

PCB Mount Header, Vertical, Board-to-Board, 8 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers



Connector Profile	Standard	
Primary Product Color	Black	
Contact Features		
Mating Square Post Dimension	.64 mm[.025 in]	
PCB Contact Termination Area Plating Material Thickness	2.54 – 5.08 μm[100 – 200 μin]	
Contact Shape & Form	Square	
Contact Underplating Material	Nickel	
PCB Contact Termination Area Plating Material	Tin-Lead	
Contact Base Material	Phosphor Bronze	
Contact Mating Area Plating Material	Gold	
Contact Mating Area Plating Material Thickness	.762 μm[30 μin]	
Contact Type	Pin	
Contact Current Rating (Max)	3 A	
Termination Features		
Square Termination Post & Tail Dimension	.64 mm[.025 in]	
Termination Post & Tail Length	3.18 mm[.125 in]	
Termination Method to Printed Circuit Board	Through Hole - Solder	

## Mechanical Attachment

Mating Retention	With
Mating Retention Type	Detent Window
Mating Alignment	With
Mating Alignment Type	Polarization
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	2.54 mm[.1 in]
Housing Material	Thermoplastic
Dimensions	
Row-to-Row Spacing	2.54 mm[.1 in]
PCB Thickness (Recommended)	1.4 mm[.055 in]
Usage Conditions	

PCB Mount Header, Vertical, Board-to-Board, 8 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers



Housing Temperature Rating	Standard
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
Agency/Standard	CSA
Approved Standards	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	184
Packaging Type	Tray
<b>Product Compliance</b> For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Not Compliant
EU ELV Directive 2000/53/EC	Not Compliant

China RoHS 2 Directive MIIT Order No 32, 2016

Restricted Materials Above Threshold

## EU REACH Regulation (EC) No. 1907/2006 Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 2022 (223) SVHC > Threshold: Pb (40% in Component Part) Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location. BFR/CFR/PVC Free, but Br/Cl >900 ppm in other sources. Solder Process Capability Wave solder capable to 240°C

#### Halogen Content

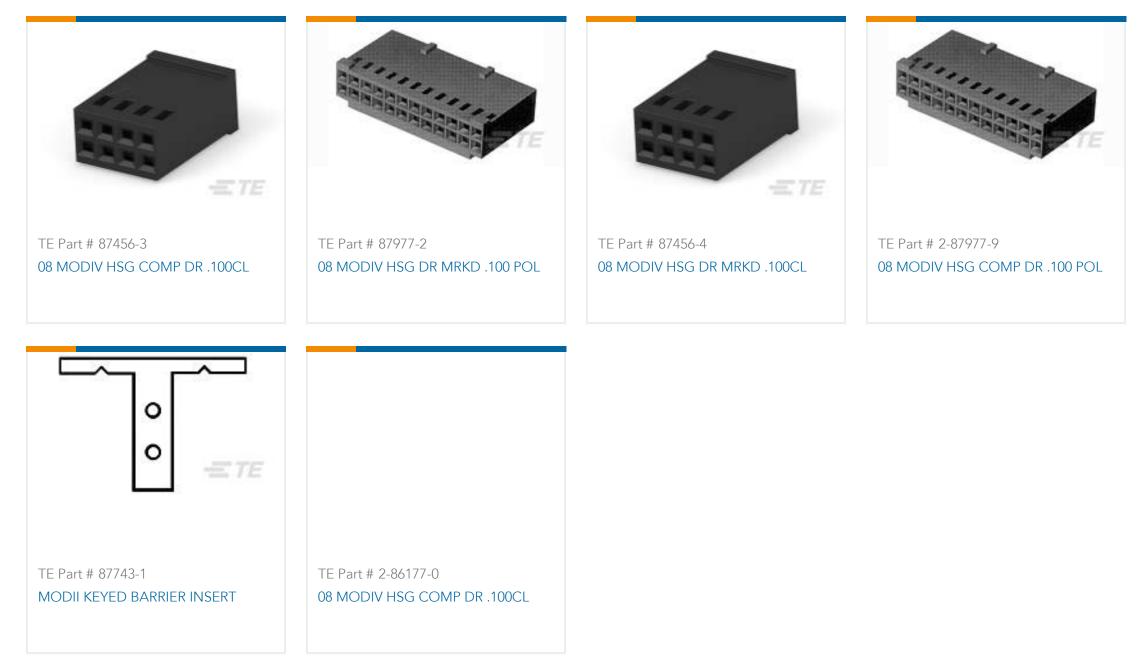
#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

PCB Mount Header, Vertical, Board-to-Board, 8 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers



## **Compatible Parts**



# Also in the Series AMPMODU Headers

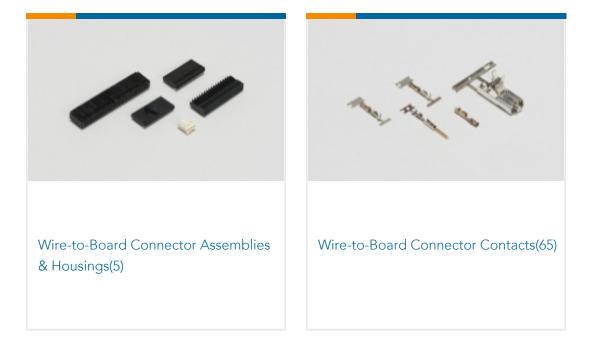








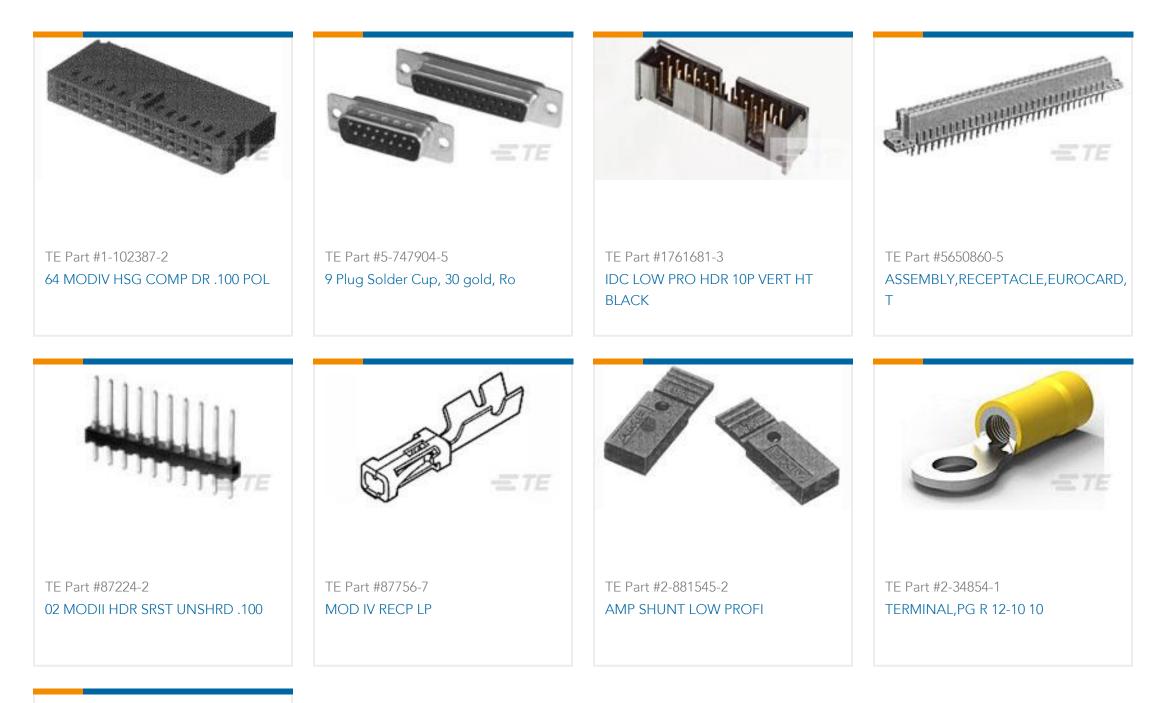
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PCB Connector Mounting(1)	PCB Connector Shrouds(1)	PCB Headers & Receptacles(4961)	PCB Latches, Locks & Retainers(2)



## Customers Also Bought

PCB Mount Header, Vertical, Board-to-Board, 8 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers







TE Part #2301840-1 AMPL REC HD20, VERT, 15P, B/L,4-40 S/LOC

## Documents

Product Drawings 08 MODII HDR DRST SHRD .100CL

English

CAD Files

3D PDF

3D

Customer View Model

ENG\_CVM\_CVM\_103168-2\_M.2d\_dxf.zip

English

Customer View Model

ENG\_CVM\_CVM\_103168-2\_M.3d\_igs.zip

English

Customer View Model

ENG\_CVM\_CVM\_103168-2\_M.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

**Product Environmental Compliance** 

**C** For support call+1 800 522 6752

PCB Mount Header, Vertical, Board-to-Board, 8 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers



**TE Material Declaration** 

English